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Part Number:	<u>0736440217</u>		~~~~
Status:	Active		See See
Overview:	HDM Backplane Co	onnector System	
Description:	HDM Board-to-Boa	rd Backplane Header, Vertical, SMC, Press-Fit, Guide Post Location	
	A, Polarizing Key P	Position N/A, 72 Circuits, Mating Length 6.00mm	
Documents:			
3D Model		Packaging Specification PK-70873-0818-001 (PDF)	
<u>3D Model (PDF)</u>		RoHS Certificate of Compliance (PDF)	8 ~ 2
Drawing (PDF)			Series image - Reference only
			Series intage - Reference only
Agency Certification			
CSA		LR19980	<u>EU ELV</u>
UL		E29179	Not Relevant
General			EU RoHS China RoHS
Product Family		Backplane Connectors	
		Backplane Connectors	Compliant
Series		73644 Baskalans	REACH SVHC
Application		Backplane	Not Contained Per -
Comments		Standard Press-Fit	D(2020)9139-DC (19
Component Type		PCB Header	Jan 2021)
Overview		HDM Backplane Connector System	Halogen-Free
Product Name		HDM	<u>Status</u>
UPC		800755022957	Low-Halogen
Physical			For more information, please visit <u>Contact US</u>
Circuits (Loaded)		72	China ROHS Green Image
Circuits (maximum)		72	ELV Not Relevant
Color - Resin		Black, Natural	RoHS Phthalates Not Contained
Durability (mating cycl	les max)	250	RONS FILIAIALES NOL CONTAINED
First Mate / Last Breal	,	No	
Flammability	ĸ	94V-0	
		Yes	Search Parts in this Series
Guide to Mating Part Keying to Mating Part		None	73644 Series
, , , ,			
Material - Metal		Phosphor Bronze, Stainless Steel	Mates With
Material - Plating Mating		Gold	73632 HDM+ Board-to-Board Daughtercard
Material - Plating Termination		Gold	Receptacle. 73780 HDM Board-to-Board
Material - Resin		High Temperature Thermoplastic	Daughtercard Receptacle
Net Weight		5.610/g	
Number of Columns		12 0	
Number of Pairs		Open Pin Field	Application Tooling FAQ
Number of Rows		6	Tooling specifications and manuals are
Orientation		Vertical	found by selecting the products below.
PC Tail Length		3.50mm	Crimp Height Specifications are then
PCB Locator		No	contained in the Application Tooling
PCB Retention		Yes	Specification document.
PCB Thickness - Reco	ommended	2.50mm	Global
Packaging Type		Tube	Description Product #
Pitch - Mating Interfac		2.00mm	Extraction Tool <u>621001000</u>
Pitch - Termination Int	terface	2.00mm	
Plating min - Mating		0.762µm	
Plating min - Terminat	tion	0.051µm	
Polarized to PCB		No	
Stackable		Yes	
Surface Mount Compa	atible (SMC)	Yes	
Temperature Range -		-55° to +105°C	
Termination Interface: Style		Through Hole - Compliant Pin	
remination interrace:	Siyle	i niougn noie - Compliant Pin	

Electrical		
Current - Maximum per Contact	1.0A	
Data Rate	1.0 Gbps	
Real Signals (per 25mm)	75	
Shielded	No	
Voltage - Maximum	250V AC	
Solder Process Data		
Lead-freeProcess Capability	N/A	
Material Info		
Reference - Drawing Numbers		
Packaging Specification	PK-70873-0818-001	

Sales Drawing

PK-70873-0818-001 SDA-73644-XXXX-001, SDA-73644-XXXX-002

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